

Amendments to the Abstract

Please replace the earlier submitted replacement Abstract with the following amended Abstract. Appendix B (attached to the Remarks) includes a clean copy of the amended Abstract.

Abstract

In a semiconductor integrated circuit device and a semiconductor integrated circuit chip, a circuit forming layer, on which are formed a large number of circuits, is formed on one surface side of a plate-like semiconductor chip, and on the other, opposing surface side thereof, a heat transfer layer is connected therewith in one body. This heat transfer layer is made of a material similar to that of the semiconductor chip, and has formed therein passage ducts to build up a closed flow passage. Within this closed flow passage is enclosed an operating fluid, and there is provided a driving means, such as a resistor film, of the operating fluid. Vibration is given to the operating fluid by the driving means, thereby transferring/diffusing a local increase of temperatures-temperature generated within the circuit-forming layer.